EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	1537	(impact$3 inject$3) with abrasive with particle	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 16:44
L3	119	(impact$3 inject$3) with abrasive with particle with (substrate wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 16:44
L4	6578183	(@ad>"20040716" @prad>"20040716" @rlad>"20040716")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 16:45
L5	69	3 not L4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 16:45
L6	17	3 and discharge not L4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 16:52
L7	8	abrasive with particle with inject$3 with wafer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 16:54
L8	5	abrasive with particle with inject$3 with wafer not 4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 16:54
L11	2	abrasive with particle with impact$3 with ion not 4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 17:11

L12	888	abrasive with particle with impact$3 not 4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 17:12
L13	5	abrasive with particle with impact$3 with plasma not 4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 17:12
L14	629	impact$3 with ion with wafer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 17:13
L15	123	impact$3 with ion with wafer with plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 17:14
L16	50	impact$3 with ion with wafer with plasma not 4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 17:14
L21	314	(yoshiyuki with abe).in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 18:02
L22	2	(yoshiyuki with abe).in. and grind$3 and crush	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 18:03
L23	7	((wafer substrate) and grind$3 and particle and crush).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 18:03
L24	64	((wafer substrate) and grind$3 and particle and ion).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 18:04

L25	12	((wafer substrate) and grind $3 and particle and ion and plasma).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 18:04
S1	6578183	(@ad>"20040716" @prad>"20040716" @rlad>"20040716")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 09:37
S2	3105892	(wafer substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 09:37
S3	63269	grind$3 same powder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 09:37
S4	12973	S2 and S3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 09:38
S5	2407	S2 same S3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 09:38
S6	1741	(wafer substrate) with grind $3 with particle	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 09:38
S7	93	(wafer substrate) with grind $3 with particle with thickness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 09:39
S8	8	("2003077854" "2003088959").pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 10:11

S9	0	("2003077854" "2003088959").pn.	US-PGPUB; USPAT	OR	ON	2009/04/16 10:12
S10	1	("20030077854" "2003088959").pn.	US-PGPUB; USPAT	OR	ON	2009/04/16 10:13
S11	2	("20030077854" "20030088959").pn.	US-PGPUB; USPAT	OR	ON	2009/04/16 10:13
S12	2	jp-2003332276-$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 10:19
S13	3669	(crush or "crystal defective") with (layer film)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 10:22
S15	99	amorphous same polycrystalline same crack	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 10:23
S16	60	(amorphous same polycrystalline same crack) with (layer film)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 10:23
S17	44	(amorphous same polycrystalline same crack) with (layer film) not S1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 10:23
S18	2	"20080318362".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 10:32
S19	2323	"quadrature.m"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 10:34
S20	142	"quadrature.m" with (wafer substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 10:36

S24	182	(chuichi with miyazaki).in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 12:50
S25	18	(chuichi with miyazaki).in. and grind$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 12:50
S26	16	("6750074" "20030088959" "6908784" "6165873" "7122447" "6812064" "7157353").pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 12:51
S27	4	("20040097054" | "20050233547").PN. OR ("7122447").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/04/16 12:52
S28	3	("5122481" | "6927167" | "7122447").PN. OR ("7335574").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/04/16 12:54
S29	11	("20020158333" | "20020167006" | "20030022464" | "20030052400" | "20030119281" | "20030119332" | "20030122232" | "20030132530" | "5242862").PN. OR ("6927167").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/04/16 12:55
S30	3	("5122481" | "6927167" | "7122447").PN. OR ("7335574").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/04/16 12:56
S31	1	"20040119088"	US-PGPUB; USPAT; USOCR	OR	ON	2009/04/16 12:59
S32	17	("4226056" | "4411107" | "4587771" | "4947598" | "5035087").PN. OR ("5122481").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/04/16 13:00
S33	8	(crush with amorphous) with layer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 13:53
S34	1	(crush with amorphous with crack)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 13:54

S35	1	(crush same amorphous same crack) same grind$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 13:55
S36	3596	(crush same grind$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 13:58
S37	204	(crush same grind$3) same layer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 13:58
S38	1	"crush layer" same grind$3 same substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 14:11
S39	6	"crush layer" same grind$3 same wafer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/16 14:11

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